

1. Record Nr.	UNINA9910457066503321
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Titolo	Understanding fabless IC technology [[electronic resource] /] / George S. Hurtarte, Evert A. Wolsheimer, Lisa M. Tafoya
Pubbl/distr/stampa	Amsterdam ; ; Boston, : Elsevier/Newnes, c2007
ISBN	1-281-03653-6 9786611036539 0-08-055119-X
Edizione	[1st edition]
Descrizione fisica	1 online resource (294 p.)
Collana	Communications engineering series
Altri autori (Persone)	WolsheimerEvert A TafoyaLisa M
Disciplina	621.3815
Soggetti	Integrated circuits - Design and construction Integrated circuits industry Electronic books.
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references (p. 243-245) and index.
Nota di contenuto	Front Cover; Understanding Fabless IC Technology; Copyright Page; Contents; Acknowledgements; Preface; PART 1 - Manufacturing Strategies: Understanding Fabless IC Technology; Chapter 1: More than a Decade of Transition in the Semiconductor Industry; 1.1 FSA is Established; 1.2 Early Success; 1.3 Early Success Trend Continues; 1.4 Semiconductor Business Models; 1.5 Outsourcing Will Accelerate; 1.6 IDMs are Going Fabless; 1.7 A Case Study: Cypress Semiconductor; 1.8 More IDMs are Outsourcing; 1.9 Geographic Manufacturing Centers; Chapter 2: Fabless Semiconductor Manufacturing 2.1 Foundry Revenue Growth 2.2 Semiconductor Back-End Services; 2.3 Semiconductor Equipment; Chapter 3: Qualities of Successful Fabless Companies; 3.1 Defining Events for the Fabless Market; 3.2 Thriving in the Fabless Model; 3.3 Key Qualities for Success; 3.4 The Future of Fabless; PART 2 - An In-Depth Understanding of the Fabless Semiconductor Business Model; Chapter 4: Semiconductor Manufacturing Basics; 4.1 Semiconductor Processes; 4.2 Semiconductor Manufacturing Steps; 4.3 Wafer Size; 4.4 Manufacturing Costs; 4.5 Conclusion; Chapter 5: Fabless ASICs; 5.1 Introduction

5.2 Origins of the ASIC Industry; 5.3 Emergence of the Fabless ASIC Business Model; 5.4 The Fabless ASIC Model: How It Works; 5.5 The Services and Capabilities of a Fabless ASIC Supplier; 5.6 Conclusion; Chapter 6: Electronic Design Automation; 6.1 Fabless EDA Overview; 6.2 Fabless EDA Selection Process; 6.3 Physical Design EDA; Chapter 7: Intellectual Property; 7.1 SIP Industry Overview; 7.2 SIP Business Environment; 7.3 Sourcing SIP Products; 7.4 Baseline Terminology; 7.5 Finding SIP and Related Products; 7.6 Evaluating SIP Business Models; 7.7 SIP Product Enablers; 7.8 Examples by SIP Product Type; 7.9 Licensing SIP Products; 7.10 Provider and Buyer Perspectives; 7.11 The Evolution of the IP Industry; 7.12 Intellectual Property Considerations; 7.13 IP Outsourcing; 7.14 Making IP Work in the Fabless Semiconductor Community; 7.15 IP Acquisition Considerations for Fabless IC Companies; Chapter 8: e-Commerce; 8.1 The Virtual Fab Challenge; 8.2 Semiconductor & Fabless Manufacturing: What is Different?; 8.3 "Build to Forecast" for Outsourced Manufacturing; 8.4 ERP System Solutions; 8.5 The Information Ecosystem: Where Communication is Key; Chapter 9: Quality and Reliability; 9.1 General; 9.2 Front-End; 9.3 Back-End; 9.4 Environment, Health and Safety; Chapter 10: Test Development; 10.1 Simplifying Outsourced Test Development; 10.2 Preparation; 10.3 Evaluation; 10.4 Conclusion; PART 3 - Becoming a Best-in-Class Fabless Company; Chapter 11: Best Practices for Fabless Companies; 11.1 Achieving Best-in-Class Operations Practices; 11.2 A Foundry Manager's Role in a Fabless Company; 11.3 Closing the Loop: Understanding the Manufacturing Flow; 11.4 Managing a Virtual Manufacturing Chain; Chapter 12: Building the Right Partnerships; 12.1 Suppliers are (Almost) Just as Important as Customers

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## Sommario/riassunto

Fabless (no fabrication) IC (integrated circuit) techniques are growing rapidly and promise to become the standard method of IC manufacturing in the near future, this book will provide readers with what will soon be required knowledge of the subject. Other books on IC fabrication deal with the strictly physical process aspects of the topic and assume all factors in IC fabrication are under the control of the IC designing company. By contrast, this title recognizing that fabless IC design is often as much about managing business relationships as it is about physical processes. "Fabless? ICs are

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